



SN74LS393 (LX) Dual 4-bit Binary Ripple Counter

Product Specification

Specification Revision History:

Version	Date	Description
2023-06-A0	2023-06	New
2023-11-A1	2023-11	Parameter modification



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1、General Description

The SN74LS393 is a dual 4-stage binary ripple counter.

Features:

- Temperature range: -40°C to +125°C
- Packaging information: DIP14/SOP14/TSSOP14



Ordering Information:

Tube packing specifications:

Part number	Packaging form	Marking code	Tube quantity	Boxed tube quantity	Boxed quantity	Notes
SN74LS393N (LX)	DIP14	SN74LS393N	25 PCS/tube	40 tube/box	1000 PCS/box	Dimensions of plastic enclosure: 19.0mm×6.4mm Pin spacing: 2.54mm
SN74LS393D(LX)	SOP14	LS393	50 PCS/tube	200 tube/box	10000 PCS/box	Dimensions of plastic enclosure: 8.7mm×3.9mm Pin spacing: 1.27mm
SN74LS393P(LX)	TSSOP14	LS393	96 PCS/tube	200 tube/box	19200 PCS/box	Dimensions of plastic enclosure: 5.0mm×4.4mm Pin spacing: 0.65mm



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Reel packing specifications:

Part number	Packaging form	Marking code	Reel quantity	Boxed reel quantity	Notes
SN74LS393DR(LX)	SOP14	LS393	2500 PCS/reel	5000 PCS/box	Dimensions of plastic enclosure: 8.7mm×3.9mm Pin spacing: 1.27mm
SN74LS393PW(LX)	TSSOP14	LS393	5000 PCS/reel	10000 PCS/box	Dimensions of plastic enclosure: 5.0mm×4.4mm Pin spacing: 0.65mm

Note 1: "XX" refers to variable content, meaning year and package batch serial number.

Note 2: If the physical information is inconsistent with the ordering information, please refer to the actual product.



2、Block Diagram And Pin Description

2.1、Block Diagram

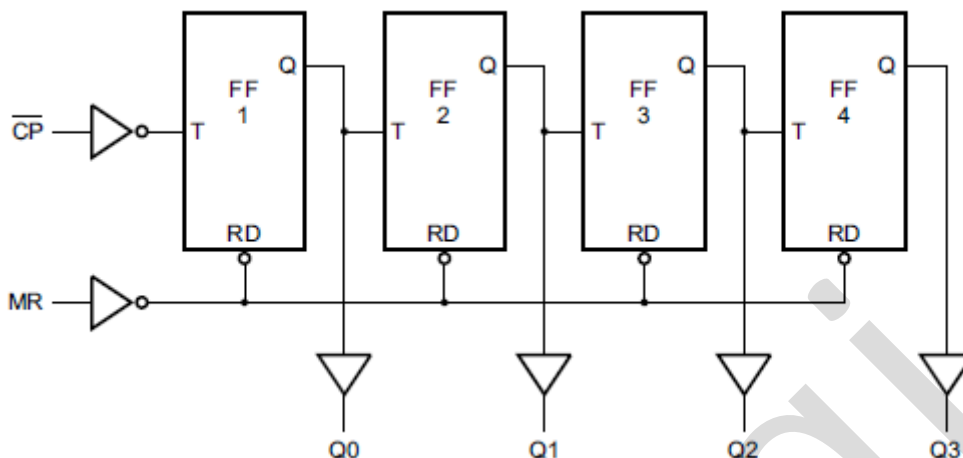
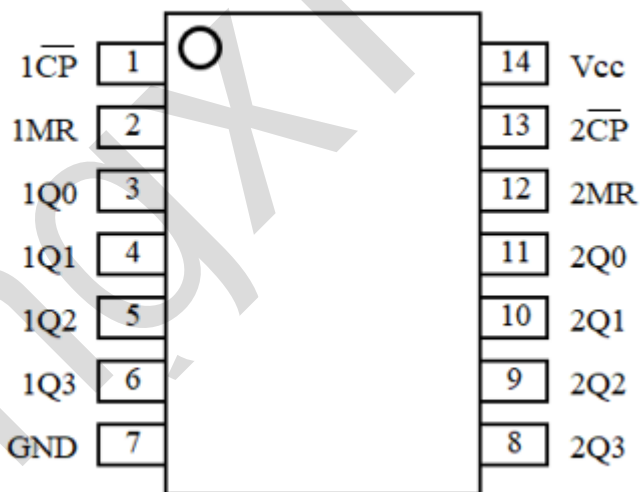


Figure 1. Logic symbol

2.2、Pin Configurations



2.3、Pin Description

Pin No.	Pin Name	Description
1	1CP	clock input (HIGH-to-LOW, edge-triggered)
2	1MR	asynchronous master reset input (active HIGH)
3	1Q0	flip-flop output
4	1Q1	flip-flop output
5	1Q2	flip-flop output
6	1Q3	flip-flop output
7	GND	ground (0V)



8	2Q3	flip-flop output
9	2Q2	flip-flop output
10	2Q1	flip-flop output
11	2Q0	flip-flop output
12	2MR	asynchronous master reset input (active HIGH)
13	2CP	clock input (HIGH-to-LOW, edge-triggered)
14	V _{CC}	supply voltage

2.4、Function Table

Count	Output			
	nQ3	nQ2	nQ1	nQ0
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H
10	H	L	H	L
11	H	L	H	H
12	H	H	L	L
13	H	H	L	H
14	H	H	H	L
15	H	H	H	H

Note: H=HIGH voltage level; L=LOW voltage level.

3、Electrical Parameter

3.1、Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit	
supply voltage	V _{CC}	-	-0.5	+7	V	
supply current	I _{CC}	-	-	50	mA	
ground current	I _{GND}	-	-50	-	mA	
input clamping current	I _{IK}	V _I < -0.5V or V _I > V _{CC} +0.5V	-	±20	mA	
output clamping current	I _{OK}	V _O < -0.5V or V _O > V _{CC} +0.5V	-	±20	mA	
output current	I _O	-0.5V < V _O < V _{CC} +0.5V	-	±25	mA	
storage temperature	T _{stg}	-	-65	+150	°C	
soldering temperature	T _L	10s	DIP		245	°C



			SOP/TSSOP	260	
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3.2、Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
ambient temperature	T_{amb}	-	-40	-	+125	°C

3.3、Electrical Characteristics

3.3.1、DC Characteristics 1

($T_{amb}=-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V_{CC}	Conditions	Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	2.0V	-	1.5	1.2	-	V
		4.5V	-	3.15	2.4	-	V
		6.0V	-	4.2	3.2	-	V
LOW-level input voltage	V_{IL}	2.0V	-	-	0.8	0.5	V
		4.5V	-	-	2.1	1.35	V
		6.0V	-	-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	2.0V	$I_O=-20\mu\text{A}$	1.9	2.0	-	V
		4.5V	$I_O=-20\mu\text{A}$	4.4	4.5	-	V
		6.0V	$I_O=-20\mu\text{A}$	5.9	6.0	-	V
		4.5V	$I_O=-4.0\text{mA}$	3.84	4.32	-	V
		6.0V	$I_O=-5.2\text{mA}$	5.34	5.81	-	V
LOW-level output voltage	V_{OL}	2.0V	$I_O=20\mu\text{A}$	-	0	0.1	V
		4.5V	$I_O=20\mu\text{A}$	-	0	0.1	V
		6.0V	$I_O=20\mu\text{A}$	-	0	0.1	V
		4.5V	$I_O=4.0\text{mA}$	-	0.15	0.33	V
		6.0V	$I_O=5.2\text{mA}$	-	0.16	0.33	V
input leakage current	I_I	6.0V	$V_I=V_{CC}$ or GND	-	-	± 1	μA
OFF-state output current	I_{OZ}	6.0V	$V_I=V_{IH}$ or V_{IL} ; $V_O=V_{CC}$ or GND	-	-	± 5	μA
supply current	I_{CC}	6.0V	$V_I=V_{CC}$ or GND; $I_O=0\text{A}$	-	-	80	μA



3.3.2、DC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V _{CC}	Conditions	Min.	Typ.	Max.	Unit
HIGH-level input voltage	V _{IH}	2.0V	-	1.5	-	-	V
		4.5V	-	3.15	-	-	V
		6.0V	-	4.2	-	-	V
LOW-level input voltage	V _{IL}	2.0V	-	-	-	0.5	V
		4.5V	-	-	-	1.35	V
		6.0V	-	-	-	1.8	V
HIGH-level output voltage	V _{OH}	2.0V	I _O = -20uA	1.9	-	-	V
		4.5V	I _O = -20uA	4.4	-	-	V
		6.0V	I _O = -20uA	5.9	-	-	V
		4.5V	I _O = -4.0mA	3.7	-	-	V
		6.0V	I _O = -5.2mA	5.2	-	-	V
LOW-level output voltage	V _{OL}	2.0V	I _O = 20uA	-	-	0.1	V
		4.5V	I _O = 20uA	-	-	0.1	V
		6.0V	I _O = 20uA	-	-	0.1	V
		4.5V	I _O = 4.0mA	-	-	0.4	V
		6.0V	I _O = 5.2mA	-	-	0.4	V
input leakage current	I _I	6.0V	V _I = V _{CC} or GND	-	-	±1	uA
OFF-state output current	I _{OZ}	6.0V	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND	-	-	±10	uA
supply current	I _{CC}	6.0V	V _I = V _{CC} or GND; I _O = 0A	-	-	160	uA



3.3.3、AC Characteristics 1

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V _{CC}	Conditions	Min.	Typ.	Max.	Unit	
nCP to nQ0 propagation delay	t _{PLH} , t _{PHL}	2.0V	C _L =50pF	-	41	155	ns	
		4.5V	C _L =50pF	-	15	31	ns	
		5.0V	C _L =15pF	-	12	-	ns	
		6.0V	C _L =50pF	-	12	26	ns	
nQx to nQ(x+1) propagation delay		2.0V	C _L =50pF	see Figure 4	-	14	55	ns
		4.5V	C _L =50pF		-	5	11	ns
		5.0V	C _L =15pF		-	5	-	ns
		6.0V	C _L =50pF		-	4	9	ns
nMR to nQx HIGH to LOW propagation delay	t _{PHL}	2.0V	C _L =50pF	-	39	175	ns	
		4.5V	C _L =50pF	-	14	35	ns	
		5.0V	C _L =15pF	-	11	-	ns	
		6.0V	C _L =50pF	-	11	30	ns	
transition time	t _{THL} , t _{TLH}	2.0V	C _L =50pF	-	19	95	ns	
		4.5V	C _L =50pF	-	7	19	ns	
		6.0V	C _L =50pF	-	6	16	ns	
nCP HIGH or LOW pulse width	t _w	2.0V	C _L =50pF	100	17	-	ns	
		4.5V	C _L =50pF	20	6	-	ns	
		6.0V	C _L =50pF	17	5	-	ns	
nMR HIGH pulse width		2.0V	C _L =50pF	100	19	-	ns	
		4.5V	C _L =50pF	20	7	-	ns	
		6.0V	C _L =50pF	17	6	-	ns	
nMR to nCP recovery time	t _{rec}	2.0V	C _L =50pF	5	3	-	ns	
		4.5V	C _L =50pF	5	1	-	ns	
		6.0V	C _L =50pF	5	1	-	ns	
maximum clock frequency	f _{clk(max)})	2.0V	C _L =50pF	5	30	-	MHZ	
		4.5V	C _L =50pF	24	90	-	MHZ	
		5.0V	C _L =15pF	-	99	-	MHZ	
		6.0V	C _L =50pF	28	107	-	MHZ	



3.3.4、AC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	V _{CC}	Conditions	Min.	Typ.	Max.	Unit	
nCP to nQ0 propagation delay		2.0V	C _L =50pF	see Figure 4	-	-	190	ns
		4.5V	C _L =50pF		-	-	38	ns
		6.0V	C _L =50pF		-	-	32	ns
nQx to nQ(x+1) propagation delay	t _{PLH} , t _{PHL}	2.0V	C _L =50pF	see Figure 4	-	-	70	ns
		4.5V	C _L =50pF		-	-	14	ns
		6.0V	C _L =50pF		-	-	12	ns
nMR to nQx HIGH to LOW propagation delay	t _{PHL}	2.0V	C _L =50pF	see Figure 5	-	-	210	ns
		4.5V	C _L =50pF		-	-	42	ns
		6.0V	C _L =50pF		-	-	36	ns
transition time	t _{THL} , t _{TLH}	2.0V	C _L =50pF	see Figure 4	-	-	110	ns
		4.5V	C _L =50pF		-	-	22	ns
		6.0V	C _L =50pF		-	-	19	ns
nCP HIGH or LOW pulse width	t _w	2.0V	C _L =50pF	see Figure 4	120	-	-	ns
		4.5V	C _L =50pF		24	-	-	ns
		6.0V	C _L =50pF		20	-	-	ns
nMR HIGH pulse width		2.0V	C _L =50pF	see Figure 5	120	-	-	ns
		4.5V	C _L =50pF		24	-	-	ns
		6.0V	C _L =50pF		20	-	-	ns
nMR to nCP recovery time	t _{rec}	2.0V	C _L =50pF	see Figure 5	5	-	-	ns
		4.5V	C _L =50pF		5	-	-	ns
		6.0V	C _L =50pF		5	-	-	ns
maximum clock frequency	f _{clk(max)}	2.0V	C _L =50pF	see Figure 4	4	-	-	MHZ
		4.5V	C _L =50pF		20	-	-	MHZ
		6.0V	C _L =50pF		24	-	-	MHZ



4、Testing Circuit

4.1、AC Testing Circuit

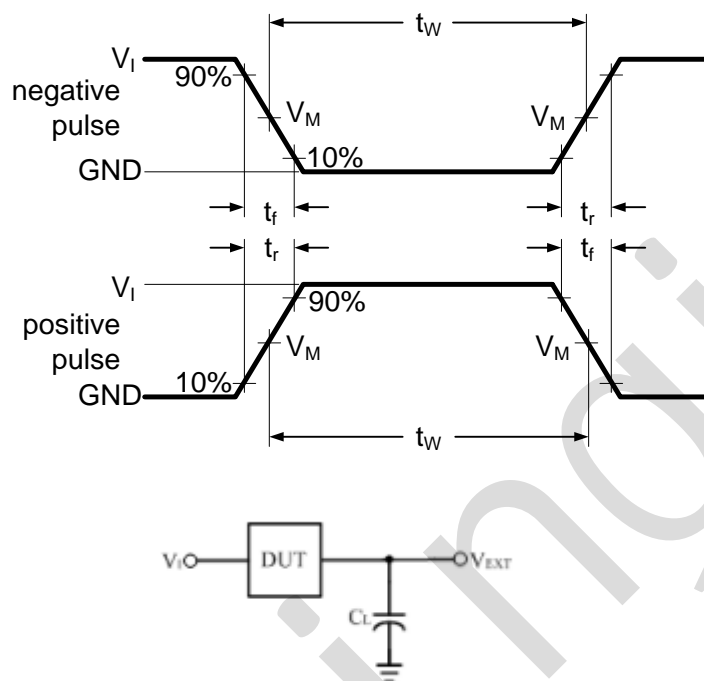


Figure 3. Test circuit for measuring switching times

C_L includes probe and jig capacitance.

4.2、Test Data

Input		Load	V_{EXT}		
V_I	$t_r = t_f$	C_L	t_{PLH}/t_{PHL}	t_{PLZ}/t_{PZL}	t_{PHZ}/t_{PZH}
V_{CC}	6.0ns	15pF, 50pF	Open	V_{CC}	GND



4.3、AC Testing Waveforms

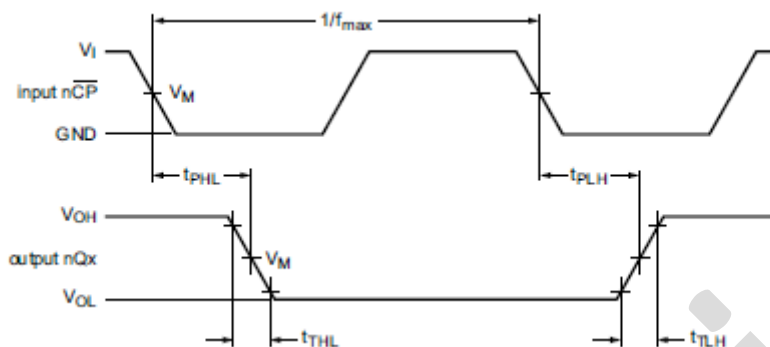


Figure 4. Propagation delay, output transition time

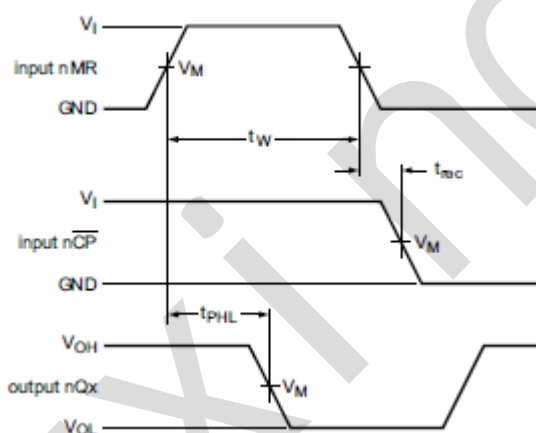


Figure 5. Propagation delays clock (nCP) to output (nQx), pulse width master reset (nMR), and recovery time master reset (nMR) to clock (nCP)

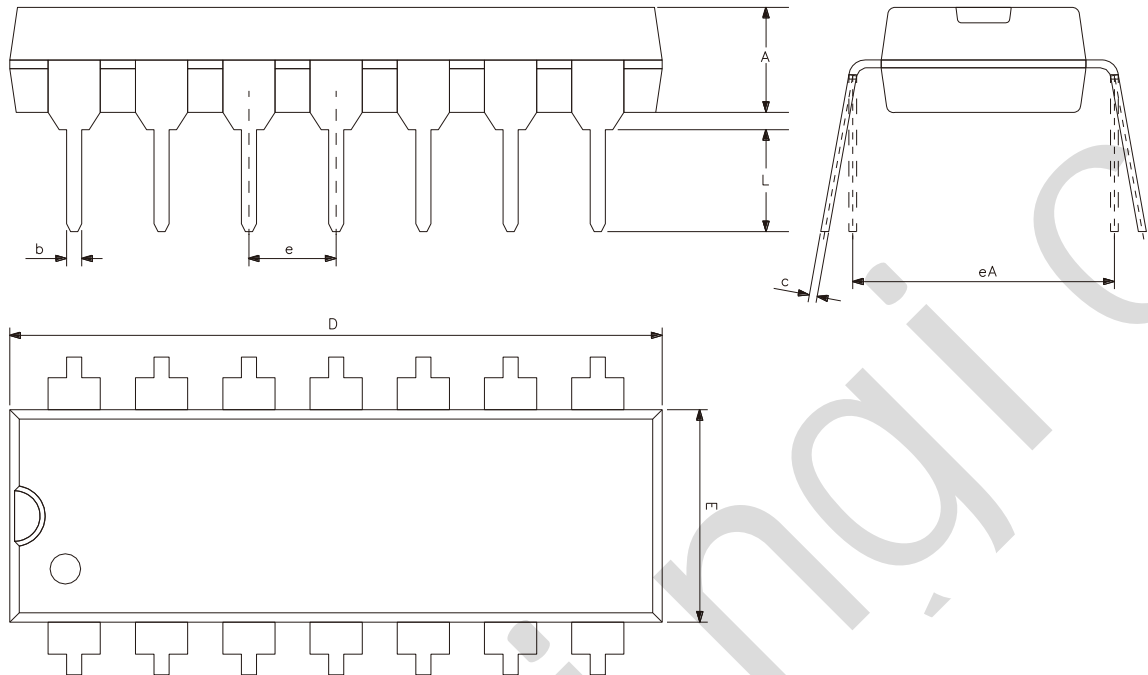
4.4、Measurement Points

Input	Output
V_M	V_M
$0.5 \times V_{CC}$	$0.5 \times V_{CC}$



5、Package Information

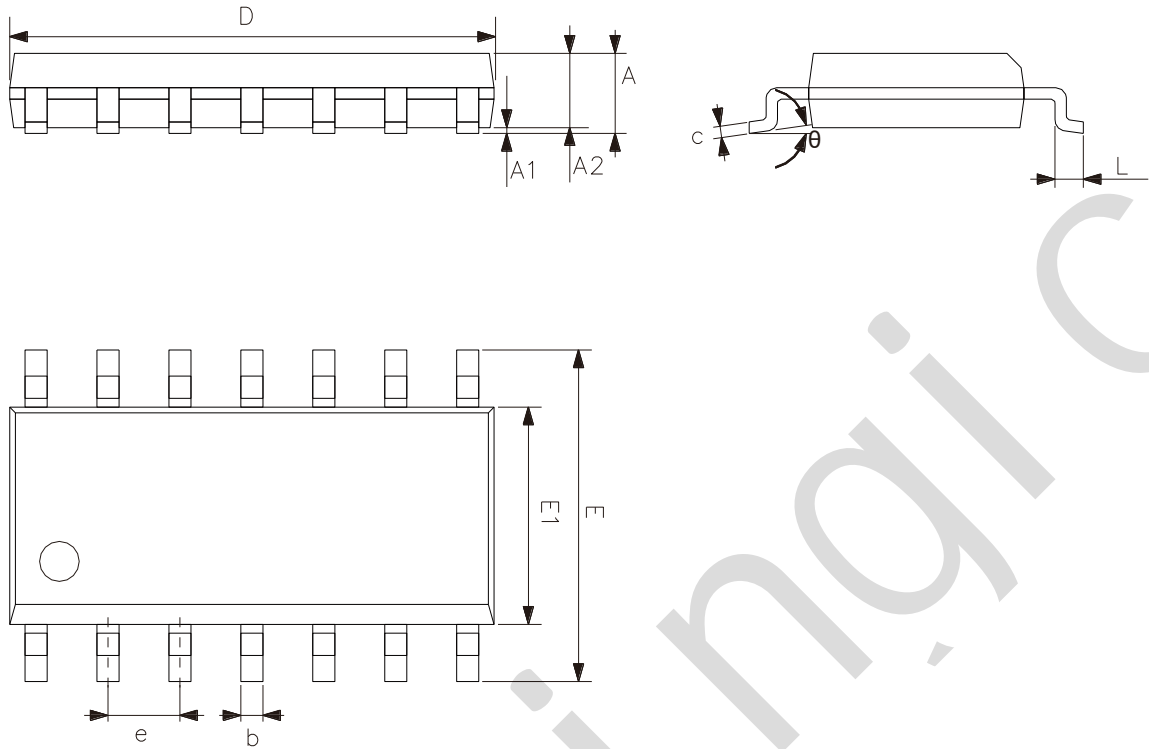
5.1、DIP14



Symbol	Dimensions (mm)	
	Min.	Max.
A	3.05	3.60
b	0.33	0.56
c	0.20	0.36
D	18.80	19.40
E	6.20	6.60
e	2.54	
eA	7.62	10.90
L	2.92	-



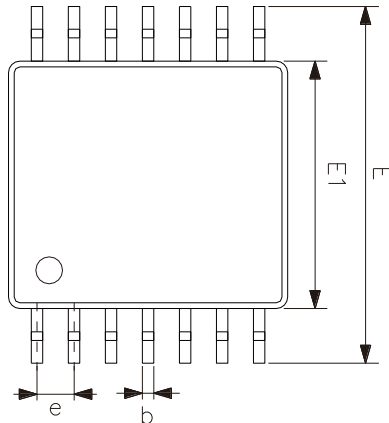
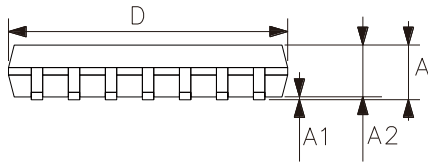
5.2、SOP14



Symbol	Dimensions (mm)	
	Min.	Max.
A	1.50	1.75
A1	0.05	0.25
A2	1.30	-
b	0.33	0.50
c	0.19	0.25
D	8.43	8.76
E	5.80	6.25
E1	3.75	4.00
e	1.27	
L	0.40	0.89
θ	0°	8°



5.3、TSSOP14



Symbol	Dimensions (mm)	
	Min.	Max.
A	-	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	4.90	5.10
E1	4.30	4.50
E	6.20	6.60
e	0.65	
L	0.45	0.75
L1	1.00	
θ	0°	8°



6、 Statements And Notes

6.1、 The name and content of Hazardous substances or Elements in the product

Part name	Hazardous substances or Elements									
	Lead and lead compounds	Mercury and mercury compounds	Cadmium and cadmium compounds	Hexavalent chromium compounds	Polybrominated biphenyls	Polybrominated biphenyl ethers	Dibutyl phthalate	Butylbenzyl phthalate	Di-2-ethylhexyl phthalate	Diisobutyl phthalate
Lead frame	○	○	○	○	○	○	○	○	○	○
Plastic resin	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
The lead	○	○	○	○	○	○	○	○	○	○
Plastic sheet installed	○	○	○	○	○	○	○	○	○	○
explanation	<p>○: Indicates that the content of hazardous substances or elements in the detection limit of the following the SJ/T11363-2006 standard.</p> <p>×: Indicates that the content of hazardous substances or elements exceeding the SJ/T11363-2006 Standard limit requirements.</p>									

6.2、 Notes

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